

REACTIVE HOT MELT ADHESIVE

Patent Number: JP2000086998
Publication date: 2000-03-28
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Requested Patent: JP2000086998
Application Number: JP19990172344 19990618
Priority Number(s):
IPC Classification: C09J157/00; C09J133/00
EC Classification:
Equivalents:

Abstract

PROBLEM TO BE SOLVED: To obtain a reactive hot melt adhesive having excellent thermal stability, especially excellent viscosity stability, when heated, capable of being set to an arbitrary reaction rate, capable of thermally actively adhering at low temperature, and having good heat resistance by using a vinylic polymer having specific crosslinking groups as a main component.

SOLUTION: This reactive hot melt adhesive contains a vinylic polymer having a crosslinking silyl group of the formula: $[\text{Si}(\text{R}_1)_2\text{-b}(\text{Y})\text{bO}]_m\text{-Si}(\text{R}_2)_3\text{-a}(\text{Y})_a$ [R_1, R_2 are each a 1-20C alkyl, a 6-20C aryl or the like; Y is a hydroxyl group or a hydrolyzable group; (a) is 0-3; (b) is 0-2; (m) is 0-19, provided that $(a)+(m)(b) \geq 1$] as a main component. The vinylic polymer is preferably a (meth) acrylic polymer obtained using a (meth) acrylic monomer as a monomer constituting the main chain in an amount of ≥ 40 wt.%. The vinylic polymer is preferably obtained, for example, by reacting an alkenyl-containing compound with a vinylic polymer obtained by a living radical polymerization method and subsequently reacting the obtained terminal alkenyl-containing vinylic polymer with a hydrosilane compound having the above crosslinking group.

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